

### Features

- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- Peak Breakdown Voltage 600V
- Operating temperature range 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation  $\geq$  0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm ( M Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
  - ✓ UL UL1577 (E364000)
  - ✓ VDE EN60747-5-5(VDE0884-5)
  - ✓ CQC GB4943.1, GB8898
  - ✓ IEC60065, IEC60950

### Description

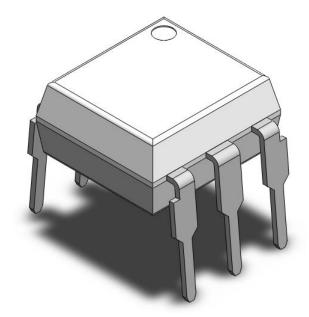
The CT3051, CT3052, CT3053 series consists of a Random Phase Photo Triac optically coupled to an Infrared-emitting diode in a 6-lead DIP package DMC-Isolator<sup>®</sup> with different lead forming options.

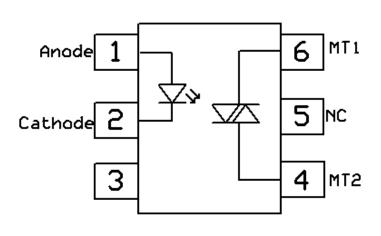
### Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

### Package Outline

### Schematic





Note: Different bending options available. See package dimension.



#### Absolute Maximum Ratings $T_A = 25^{\circ}C$ , unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	VRMS	
TOPR	Operating temperature	-55 ~ +100	°C	
Tstg	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature (For 10 seconds)	260	°C	
Emitter		·		
lF	Forward current	60	mA	
I <sub>F(TRANS)</sub>	Peak transient current (≤1µs P.W,300pps)	1	А	
VR	Reverse voltage	6	V	
PD	Power dissipation	100	mW	
Detector		·		
PD	Power dissipation	300	mW	
Vdrm	Off-State Output Terminal Voltage	600	V	
I <sub>TSM</sub>	Peak Repetitive Surge Current	1	А	



### **Electrical Characteristics** $T_A = 25^{\circ}C$ , unless otherwise specified

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I <sub>F</sub> =10mA	-	-	1.5	V	
I <sub>R</sub>	Reverse Current	$V_R = 6V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

#### **Detector Characteristics**

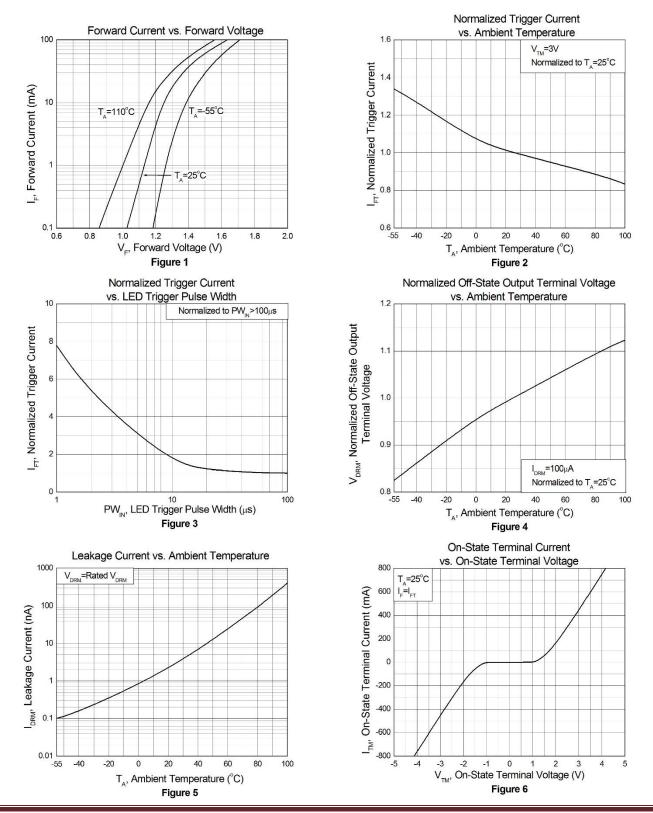
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I <sub>DRM</sub>	Peak Blocking Current	$I_{F}$ = 0mA, $V_{DRM}$ = Rated $V_{DRM}$	-	-	100	nA	
Vtm	Peak On-State Voltage	IF= Rated IFT, ITM= 100mA	-	-	2.5	V	
dv/dt	Critical Rate of Rise off-State Voltage	VPEAK= Rated VDRM	1000	-	-	V/µs	

#### **Transfer Characteristics**

Symbol	F	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
	Input	CT3051		-	-	15		
IFT	Trigger	CT3052	Terminal Voltage = 3V	-	-	10	mA	
	Current	CT3053	I™=100mA	-	-	5		
Iн	Holding Current			-	250	-	μΑ	
Rio	Isolation Re	sistance	VIO= 500VDC	1x10 <sup>11</sup>	-	-	Ω	
Сю	Isolation Ca	pacitance	f= 1MHz	-	0.25	-	pF	

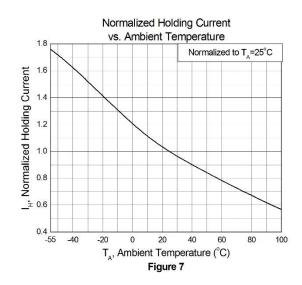


#### Typical Characteristic Curves T<sub>A</sub> = 25°C, unless otherwise specified (Continued)



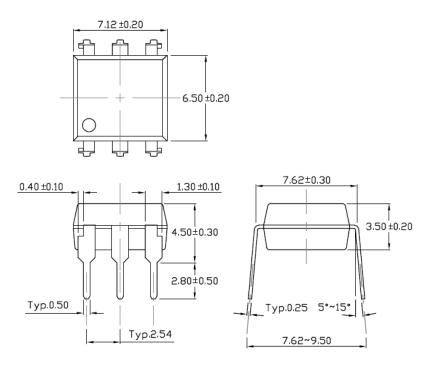


## **Typical Characteristic Curves** $T_A = 25^{\circ}C$ , unless otherwise specified (Continued)



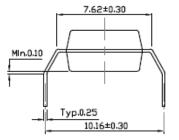


### Package Dimension Dimensions in mm unless otherwise stated

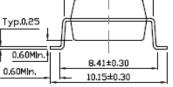


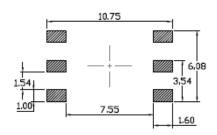
Forming Option Dimensions in mm unless otherwise stated

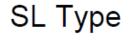
М Туре

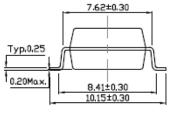


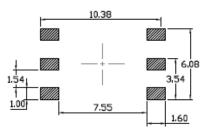






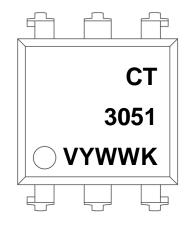








### **Marking Information**



#### Note:

- CT : Denotes "CT Micro"
- 3051 : Part Number
- X : CTR Rank Option (Blank, A or B)
- V : VDE Safety Mark Option (Blank or V)
- Y : One Digit Year Code
- WW : Two Digit Work Week
- K : Manufacturing Cod

### **Ordering Information**

### CT305X(Y)(Z)-G

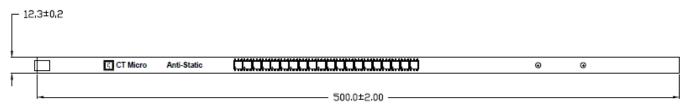
- CT = Denotes "CT Micro"
- 305X = Part No. (CT305X:0,1,2)
- V = VDE Safety Mark Option (Blank or V)
- Y = Lead Form Option (Blank, S, SL or M)
- Z = Tape and Reel Option (Blank, T1, T2, T3 or T4)
- G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
М	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming – With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel

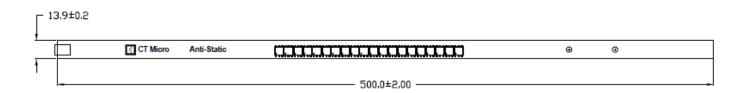


#### Carrier Specifications Dimensions in mm unless otherwise stated

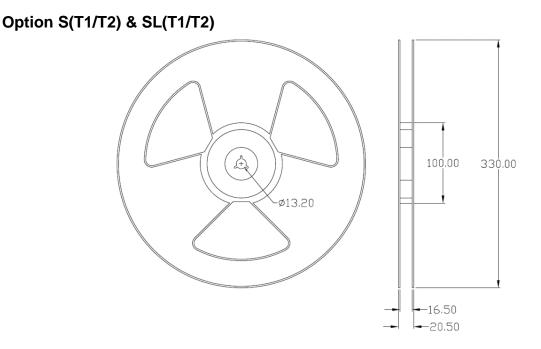
#### **Tube Option Standard DIP**



### Tube Option M Type

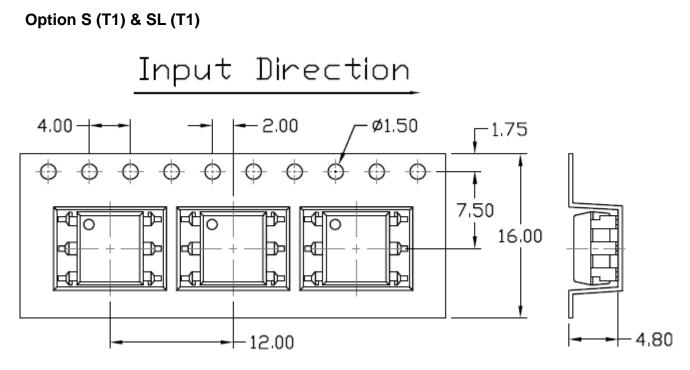


### Reel Dimension All dimensions are in mm, unless otherwise stated

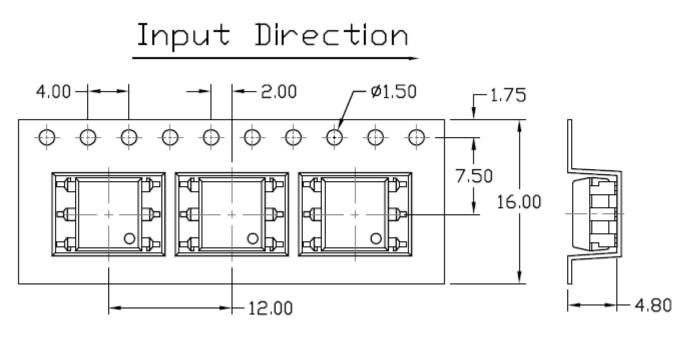




#### Carrier Tape Specifications Dimensions in mm unless otherwise stated



Option S (T2) & SL (T2)





### Solderability spec (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

### Wave soldering (follow the JEDEC standard JESD22-A111)

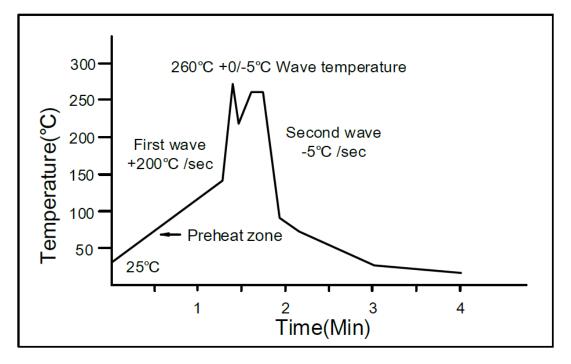
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



### Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.



### **Phototriac Optocoupler**

#### Max. Ramp-up Rate = 3° C/S Max. Ramp-down Rate = 6° C/S ТР 260 tp 240 · Tι 220 200 -Tsmax --t∟ 180 -Preheat Area ---Temperature (° C) 160 -Tsmin 140 ts 120 -100 -80 -60 -40 -20 -0 120 240 360 Time 25° C to Peak -Time (Seconds)

### **Reflow Profile (follow the JEDEC standard J-STD-020)**

Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (TL)	217°C
Time ( $t_L$ ) Maintained Above ( $T_L$ )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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